

ABSTRACT

5 A sub-fab area installation apparatus includes: a vacuum pump configured to evacuate a processing gas from a processing chamber of the semiconductor manufacturing equipment; a cooling unit configured to cool a first circulation liquid used in the processing chamber; a heating unit configured to heat a second circulation liquid used in the processing chamber; and a cooling-liquid line configured to pass a cooling liquid therethrough. The
10 cooling liquid is supplied from a cooling source. The cooling-liquid line includes: a distribution line configured to supply the cooling liquid to the vacuum pump and the cooling unit; and a merging return line configured to merge the cooling liquid that has passed through the vacuum pump and the cooling unit and return the cooling liquid to the cooling source.

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FIG. 1